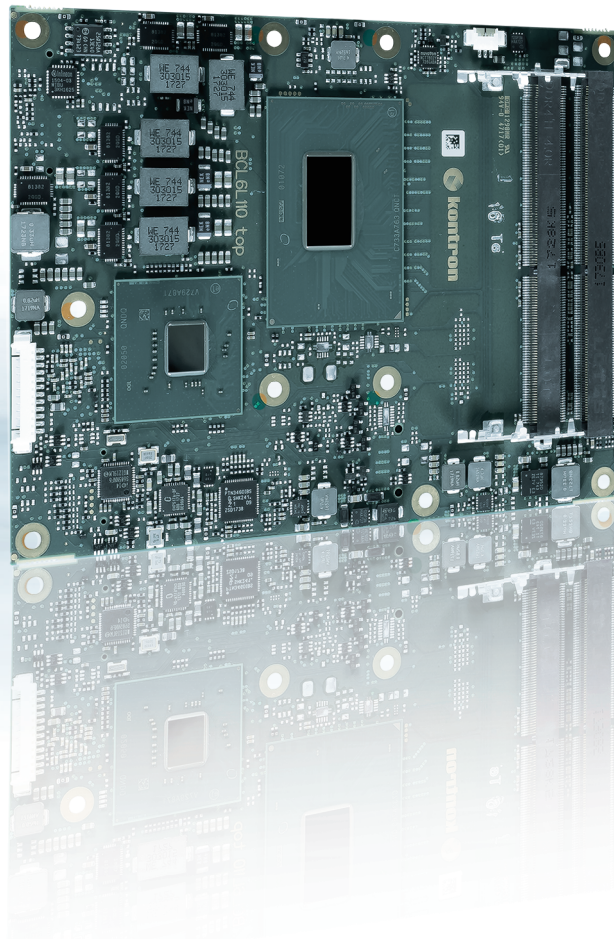


# COMe-bCL6 (R E2S)

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## COM Express® Basic Type 6 with 8th/9th Generation Intel® Core™ / Xeon® Processors

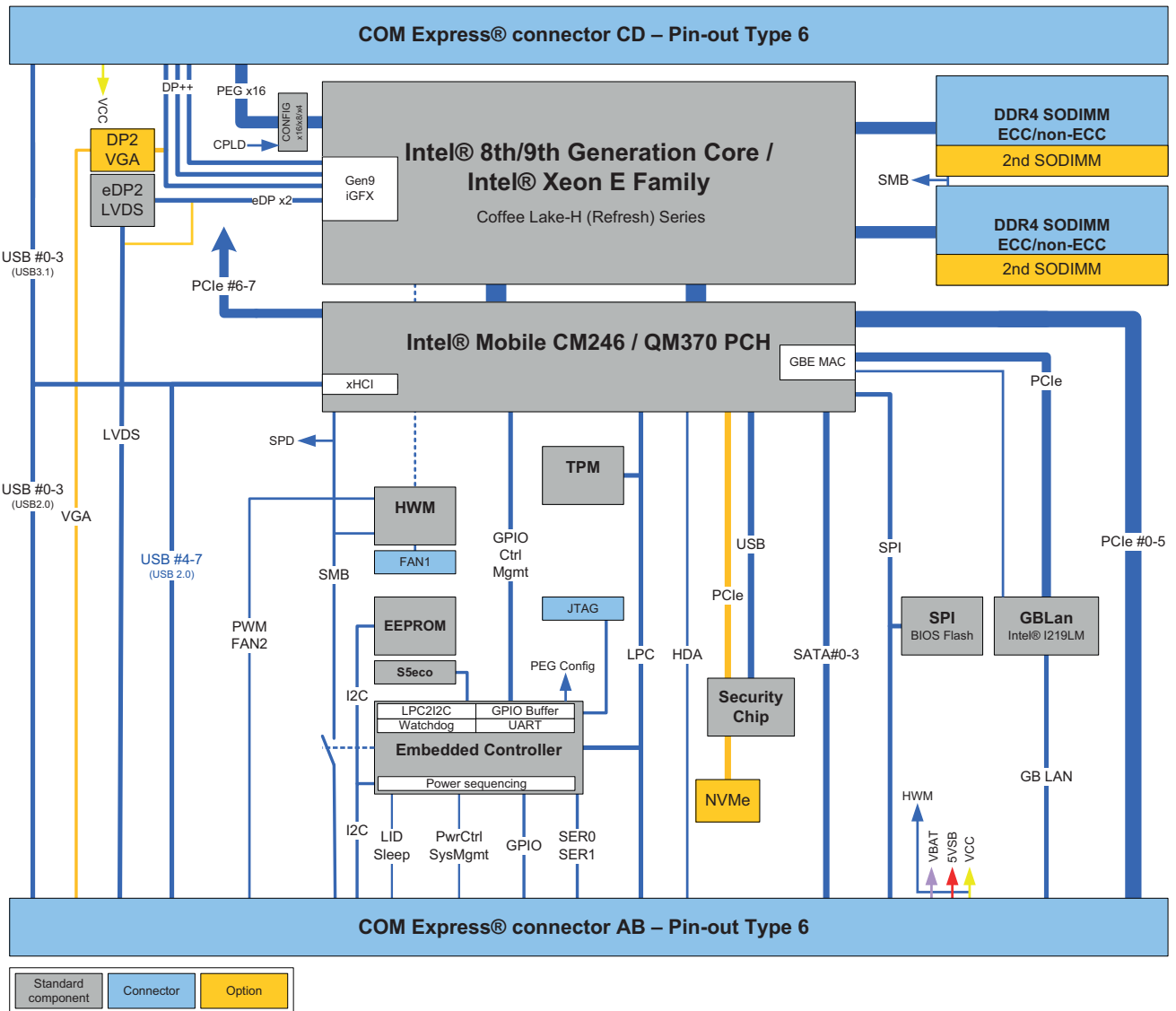
- ▶ Intel® 8th/9th Generation Core™ series / Xeon® E family with CM246/QM370 PCH
- ▶ Up to 128 GByte DDR4 non-ECC/ECC memory
- ▶ Optional NVMe SSD onboard
- ▶ Industrial grade versions
- ▶ Support of Kontron's Embedded Security Solution (APPROTECT)

POSSIBILITIES START HERE

## TECHNICAL INFORMATION

COMPLIANCE	COM Express® basic, Pin-out Type 6
DIMENSIONS (H X W)	125 x 95 mm
CPU	Intel® Xeon® 8th Gen E-2176M, 6x 2.7 GHz (4.4 GHz), GT2, 45/35 W Intel® Core™ 8th Gen i7-8850H, 6x 2.6 GHz (4.3 GHz), GT2, 45/35 W Intel® Core™ 8th Gen i5-8400H, 4x 2.5 GHz (4.2 GHz), GT2, 45/35 W Intel® Core™ 8th Gen i3-8100H, 4x 3.0 GHz, GT2, 45/35 W Intel® Xeon® 9th Gen E-2276ME (6x 2.8 GHz, GT2, 45W/35W) Intel® Xeon® 9th Gen E-2276ML (6x 2.0 GHz, GT2, 25W) Intel® Xeon® 9th Gen E-2254ME (4x 2.6 GHz, GT2, 45W/35W) Intel® Xeon® 9th Gen E-2254ML (4x 1.7 GHz, GT2, 25W) Intel® Core™ 9th Gen i7-9850HE (6x 2.7 GHz, GT2, 45W/35W) Intel® Core™ 9th Gen i7-9850HL (6x 1.9 GHz, GT2, 25W) Intel® Core™ 9th Gen i3-9100HL (4x 1.6 GHz, GT2, 25W) Intel® Pentium™ 9th Gen G5600E (2x2.6 GHz, GT2, 35W) Intel® Celeron® 9th Gen G4930E (2x2.4 GHz, GT2, 35W) Intel® Celeron® 9th Gen G4932E (2x1.9 GHz, GT2, 25W)
CHIPSET	Intel® Mobile CM246 (Xeon®) / Intel® Mobile QM370 (Core™)
MAIN MEMORY	Up to 4x DDR4-2400 SO-DIMM with up to 128 GByte (non-ECC/ECC) (3 <sup>rd</sup> /4 <sup>th</sup> socket on request)
GRAPHICS CONTROLLER	Intel® HD Graphics P630 for Xeon® processor Intel® HD Graphics 630 for Core™ processors
ETHERNET CONTROLLER	Intel® I219LM
ETHERNET	10/100/1000 MBit Ethernet
HARD DISK	4x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS® SUPPORT	8x PCIe x1, 1x PEG x16
PANEL SIGNAL	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	4x USB 3.1 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	Intel® High Definition Audio
COMMON FEATURES	SPI, LPC, SMB, Fast I <sup>2</sup> C, Staged Watchdog, RTC, support of Intel® Optane™ memory technology via PCIe
BIOS	AMI Aptio V
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)
FEATURES ON REQUEST	vPRO (AMT/TXT/AES Support), eDP instead of LVDS, VGA, Intel® Mobile HM370 Chipset, 3 <sup>rd</sup> /4 <sup>th</sup> DDR4 SO-DIMM socket, NVMe SSD
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
SPECIAL FEATURES	POSCAP capacitors, Trusted Platform Module TPM 2.0, Security Chip, 4k Resolutions, Flexible PEG lane configuration by Setup Option, Rapid shutdown (R E2S variants)
OPERATING SYSTEM	Windows® 10, Linux, VxWorks
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating Extended temperature: -25 °C to +75 °C operating, -30 °C to +85 °C non-operating Industrial temperature: -40 °C to +85 °C operating, -40 °C to +85 °C non-operating
SUPPORTED MODULES	COMe-bCL6(R E2S) xx-xxxxx CM246/QM370

► BLOCK DIAGRAM



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